



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

V. Dwyer
#17 D
12-20-00

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

RESPONSE TO SEPTEMBER 12, 2000 OFFICE ACTION

To: Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828

Sir:

Responsive to the Office Action dated September 12, 2000, Applicant amends and remarks as follows [unless otherwise indicated, deletions are bracketed, additions are underlined]:

AMENDMENTS

RECEIVED
DEC 20 2000
TC 3700 MAIL ROOM